

Boards, Chips and Packaging: Designing to Maximize Results Agenda

















7:30am - 8:30am	Registration and Continental Breakfast
8:30am - 8:45am	Welcome & Outlook - Jim Feldhan, Semico Research Corp.
8:45am - 9:15am	Michael Gay, Isola Abstract
9:15am - 9:45am	Daniel DeAraujo, Mentor Graphics Abstract
9:45am - 10:15am	Break
10:15am - 11:30am	Panel: How Do We Get to Next-Generation High Speed Data Transfer Rates?
	Moderator: Brian Fuller, ARM
	Lee Ritchey, Speeding Edge
	Scott McMorrow, Samtec
	Geoffrey Hazelett, Polar Instruments
	Daniel DeAraujo, Mentor Graphics
	Nathaniel Unger, Altera
11:45am - 12:30pm	Lunch - Sponsored by Isola
12:30pm - 1:30pm	Keynote: Chesley B. "Sully" Sullenberger, III
	Afternoon Session: Innovation Spotlight
1:30pm - 1:50pm	Robert L. Sankman, Intel Abstract
1:50pm - 2:10pm	Margaret Schmitt, Ansys Abstract
2:10pm - 2:30pm	Break
2:30pm - 3:45pm	Panel: Boards, Chips & Packaging: Meeting Market Requirements
	Moderator: Mike Noonen, Ambiq Micro
	Jason Marsh, Insulectro
	Heidi Barnes, Keysight Technologies
	Nathapong Suthiwongsunthorn, Ph.D., UTAC
	Tom Whipple, Cadence
3:45pm - 4:00pm	Closing Remarks